

### 650V 15A Field Stop Trench IGBT

V <sub>CES</sub>	650V
I <sub>C(100°C)</sub>	8A
V <sub>CE(sat) (Typ.)</sub>	1.65V@I <sub>C</sub> =15A
$P_D$	32W

#### Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Low Switching Loss
- 3) Short Circuit Withstand Time 5µs
- 4) Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 5) Pb free Lead Plating; RoHS Compliant

#### Applications

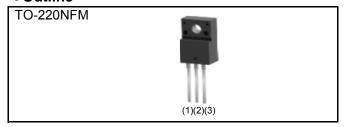
**General Inverter** 

**UPS** 

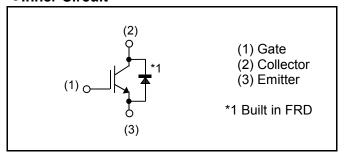
**Power Conditioner** 

Welder

#### Outline



#### ●Inner Circuit



### Packaging Specifications

	Packaging	Tube		
		Reel Size (mm)	-	
_	VDO	Tape Width (mm)	-	
Туре	ype	Basic Ordering Unit (pcs)	1,000	
		Packing Code	C9	
		Marking	RGT30TM65D	

## ● Absolute Maximum Ratings (at T<sub>C</sub> = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		$V_{CES}$	650	V
Gate - Emitter Voltage		$V_{GES}$	±30	V
Collector Current	T <sub>C</sub> = 25°C	I <sub>C</sub>	14	А
Collector Current	T <sub>C</sub> = 100°C	I <sub>C</sub>	8	А
Pulsed Collector Current		I <sub>CP</sub> *1	I <sub>CP</sub> *1 45	
Diode Forward Current	T <sub>C</sub> = 25°C	I <sub>F</sub>	17	А
	T <sub>C</sub> = 100°C	I <sub>F</sub>	9	А
Diode Pulsed Forward Current		I <sub>FP</sub> *1	45	А
Power Dissipation	T <sub>C</sub> = 25°C	P <sub>D</sub>	32	W
	T <sub>C</sub> = 100°C	$P_{D}$	16	W
Operating Junction Temperature		T <sub>j</sub>	-40 to +175	°C
Storage Temperature		T <sub>stg</sub>	-55 to +175	°C

<sup>\*1</sup> Pulse width limited by T<sub>jmax.</sub>

#### ●Thermal Resistance

Parameter	Symbol	Values			Unit
- Farameter		Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	ı	4.59	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	1	5.44	°C/W

# ullet IGBT Electrical Characteristics (at $T_j$ = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV <sub>CES</sub>	$I_C = 10 \mu A, V_{GE} = 0 V$	650	-	-	V
Collector Cut - off Current	I <sub>CES</sub>	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	1	1	10	μΑ
Gate - Emitter Leakage Current	I <sub>GES</sub>	$V_{GE} = \pm 30V, V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{\text{GE(th)}}$	V <sub>CE</sub> = 5V, I <sub>C</sub> = 10.0mA	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_C = 15A, V_{GE} = 15V$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	-	1.65 2.15	2.1 -	V

# ●IGBT Electrical Characteristics (at T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Conditions		Unit			
- Farameter	Syllibol	Conditions	Min.	Тур.	Max.	Ullit	
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> = 30V	-	780	-		
Output Capacitance	C <sub>oes</sub>	V <sub>GE</sub> = 0V	-	35	-	pF	
Reverse Transfer Capacitance	C <sub>res</sub>	f = 1MHz	-	13	-		
Total Gate Charge	Qg	V <sub>CE</sub> = 300V	-	32	-		
Gate - Emitter Charge	$Q_{ge}$	I <sub>C</sub> = 15A	-	8	-	nC	
Gate - Collector Charge	$Q_{gc}$	V <sub>GE</sub> = 15V	-	11	-		
Turn - on Delay Time	t <sub>d(on)</sub>	I <sub>C</sub> = 15A, V <sub>CC</sub> = 400V	-	18	-		
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_G = 10\Omega$	-	20	-	ns	
Turn - off Delay Time	t <sub>d(off)</sub>	T <sub>j</sub> = 25°C	-	64	-		
Fall Time	t <sub>f</sub>	Inductive Load	-	75	-		
Turn - on Delay Time	t <sub>d(on)</sub>	I <sub>C</sub> = 15A, V <sub>CC</sub> = 400V	-	18	-		
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_G = 10\Omega$	-	22	-		
Turn - off Delay Time	t <sub>d(off)</sub>	T <sub>j</sub> = 175°C	-	74	-	ns	
Fall Time	t <sub>f</sub>	Inductive Load	-	130	-		
		I <sub>C</sub> = 45A, V <sub>CC</sub> = 520V					
Reverse Bias Safe Operating Area	RBSOA	$V_P = 650V, V_{GE} = 15V$	FULL SQUARE			-	
		$R_G = 50\Omega, T_j = 175^{\circ}C$					
		V <sub>CC</sub> ≦ 360V					
Short Circuit Withstand Time	$t_{sc}$	V <sub>GE</sub> = 15V	5	-	-	μs	
		T <sub>j</sub> = 25°C					

## ●FRD Electrical Characteristics (at T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Linit
			Min.	Тур.	Max.	Unit
Diode Forward Voltage	V <sub>F</sub>	$I_F = 15A$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	- -	1.5 1.3	1.95 -	V
Diode Reverse Recovery Time	t <sub>rr</sub>	$I_F = 15A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	55	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>		-	6.0	-	А
Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	0.19	-	μC
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 15A	-	141	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	$V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	9.5	-	Α
Diode Reverse Recovery Charge	$Q_{rr}$		-	0.79	-	μC

Fig.1 Power Dissipation vs. Case Temperature

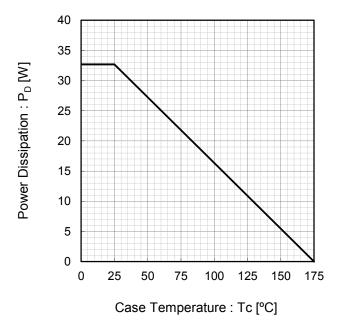


Fig.2 Collector Current vs. Case Temperature

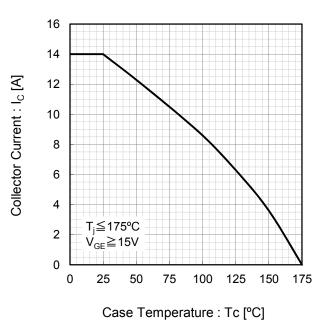


Fig.3 Forward Bias Safe Operating Area

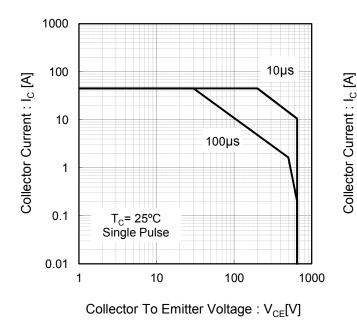
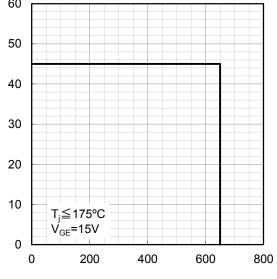


Fig.4 Reverse Bias Safe Operating Area



Collector To Emitter Voltage :  $V_{CE}[V]$ 

Fig.5 Typical Output Characteristics

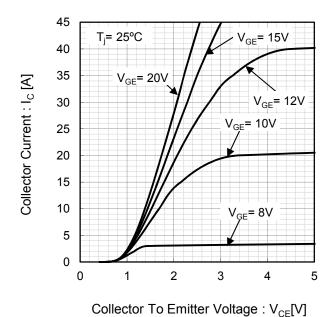
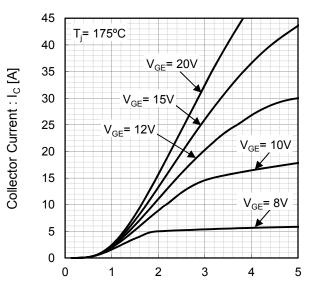


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage :  $V_{CE}[V]$ 

Fig.7 Typical Transfer Characteristics

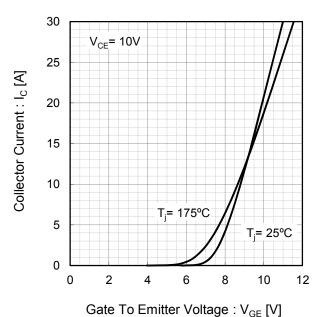


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

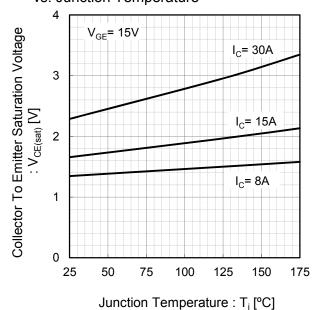
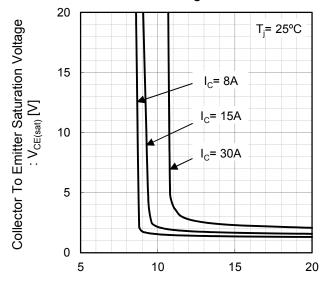
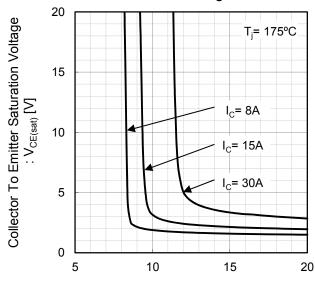


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V<sub>GE</sub> [V]

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V<sub>GE</sub> [V]

Fig.11 Typical Switching Time vs. Collector Current

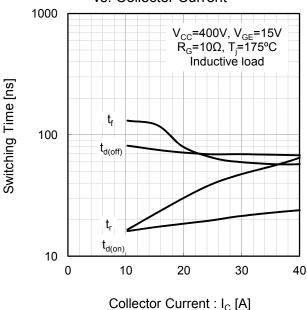
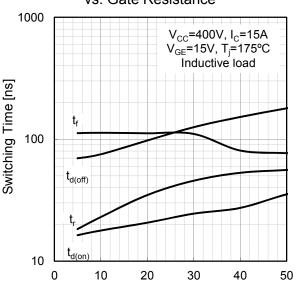


Fig.12 Typical Switching Time vs. Gate Resistance



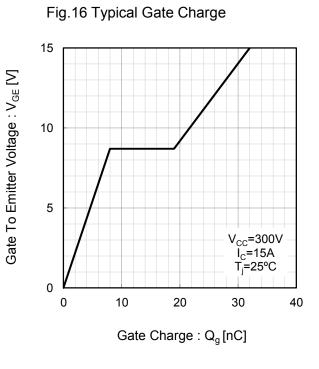
Gate Resistance :  $R_G[\Omega]$ 

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1  $\mathsf{E}_{\mathsf{off}}$  $E_{on}$ 0.1  $V_{CC}$ =400V,  $V_{GE}$ =15V  $R_{G}$ =10 $\Omega$ ,  $T_{j}$ =175°C Inductive load 0.01 0 10 20 30 40 Collector Current : I<sub>C</sub> [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] 1  $\mathsf{E}_{\mathsf{off}}$ Eon 0.1 V<sub>CC</sub>=400V, I<sub>C</sub>=15A V<sub>GE</sub>=15V, T<sub>j</sub>=175°C Inductive load 0.01 0 10 20 30 40 50 Gate Resistance :  $R_G[\Omega]$ 

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] 100 Coes 10 Cres f=1MHz V<sub>GE</sub>=0V T<sub>i</sub>=25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage : V<sub>CE</sub>[V]



vs. Forward Voltage 45 40 35 Forward Current: I<sub>F</sub> [A] 30 25 20 15 T<sub>j</sub>= 175°C 10 T<sub>i</sub>= 25°C 5 0 0.5 1.5 2 2.5 3

Fig.17 Typical Diode Forward Current

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400 V<sub>CC</sub>=400V di<sub>F</sub>/dt=200A/µs Reverse Recovery Time : t<sub>rr</sub> [ns] Inductive load 300 200 T<sub>i</sub>= 175°C 100 T<sub>i</sub>= 25°C 0 0 10 20 30 40 50 Forward Current : I<sub>F</sub> [A]

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

Forward Voltage : V<sub>F</sub>[V]

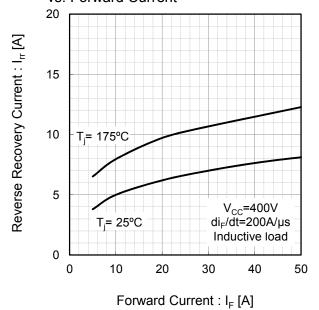


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current

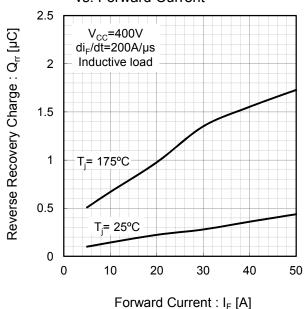


Fig.21 IGBT Transient Thermal Impedance

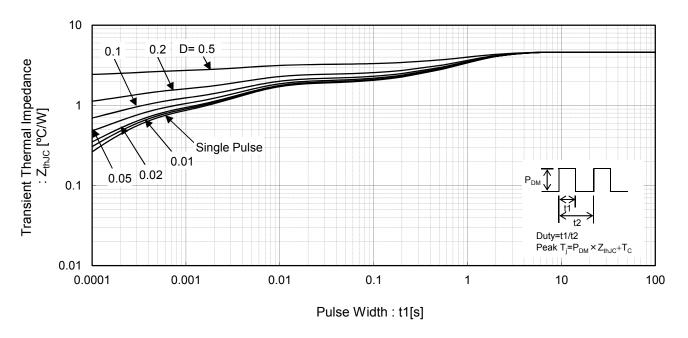
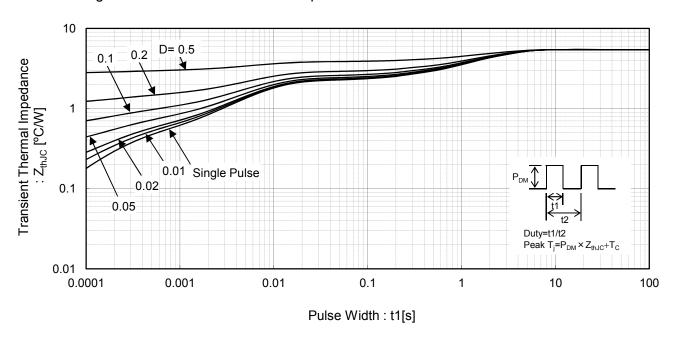


Fig.22 Diode Transient Thermal Impedance



### ●Inductive Load Switching Circuit and Waveform

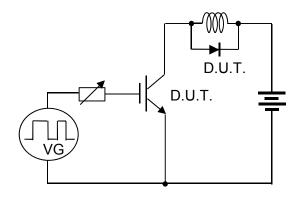


Fig.23 Inductive Load Circuit

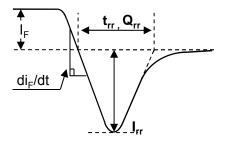


Fig.25 Diode Reverce Recovery Waveform

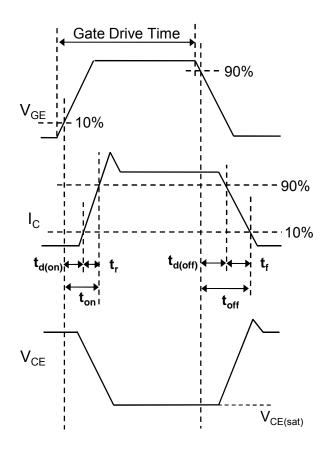


Fig.24 Inductive Load Waveform

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